PROGRAMMABLE ROM (512x4 PROM) 82S130

APRIL 1975

DIGITAL 8000 SERIES TTL/MEMORY

DESCRIPTION

The 82S130 (Open Collector Outputs) and the 82S131 (Tri-State Outputs) are Bipolar 2048-Bit Read Only Memories, organized as 512 words by 4 bits per word. They are Field-Programmable, which means that custom patterns are immediately available by following the fusing procedure given in this data sheet. The standard 82S130 and 82S131 are supplied with all outputs at logical "0". Outputs are programmed to a logic "1" level at any specified address by fusing a Ni-Cr link matrix.

The 82S130 and 82S131 are fully TTL compatible, and include on-chip decoding and one chip enable input for ease of memory expansion. They feature either Open Collector or Tri-State outputs for optimization of word expansion in bussed organizations.

Both 82S130 and 82S131 devices are available in the commercial and military temperature ranges. For the commercial temperature range (0°C to +75°C) specify N82S130/131, F. For the military temperature range $(-55^{\circ}C \text{ to } +125^{\circ}C) \text{ specify S82S130/131, F.}$

FEATURES

- ORGANIZATION 512 X 4
- ADDRESS ACCESS TIME: S82S130/131 - 70ns, MAXIMUM N82S130/131 - 50ns, MAXIMUM
- POWER DISSIPATION 0.3mW/BIT TYPICAL
- INPUT LOADING:

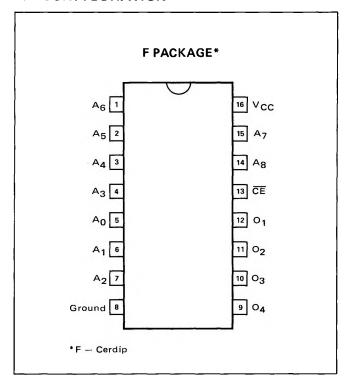
 $$82$130/131 - (-150\mu A) MAXIMUM$ $N82S130/131 - (-100\mu A) MAXIMUM$

- ONE CHIP ENABLE INPUT
- ON-CHIP ADDRESS DECODING
- OUTPUT OPTIONS: 82S130 - OPEN COLLECTOR **82S131 - TRI-STATE**
- NO SEPARATE "FUSING" PINS
- UNPROGRAMMED OUTPUTS ARE "0" LEVEL
- 16-PIN CERAMIC DIP

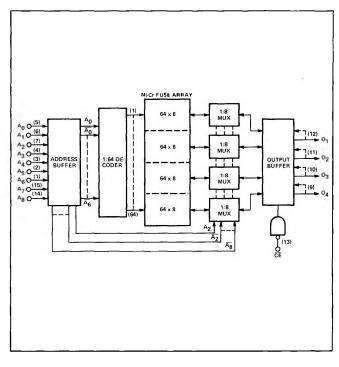
APPLICATIONS

PROTOTYPING/VOLUME PRODUCTION SEQUENTIAL CONTROLLERS **MICROPROGRAMMING** HARDWIRED ALGORITHMS **CONTROL STORE RANDOM LOGIC CODE CONVERSION**

PIN CONFIGURATION



BLOCK DIAGRAM



ABSOLUTE MAXIMUM RATINGS

	PARAMETER	RATING	UNIT
V _{CC}	Power Supply Voltage	+7	Vdc
V_{IN}	Input Voltage	+5.5	Vdc
V_{OH}	High Level Output Voltage (82S130)	+5.5	Vdc
Vo	Off-State Output Voltage (82S131)	+5.5	Vdc
TA	Operating Temperature Range (N82S130/131) (S82S130/131)	0° to +75° -55° to +125°	°c °c
T_{stg}	Storage Temperature Range	-65° to +150°	°c

ELECTRICAL CHARACTERISTICS

S82S130/131 N82S130/131 $\begin{array}{l} -55^{\circ}C\leqslant\! T_{A}\leqslant\! +125^{\circ}C,\, 4.5V\leqslant\! V_{CC}\leqslant\! 5.5V\\ 0^{\circ}C\leqslant\! T_{A}\leqslant\! +75^{\circ}C,\, 4.75V\leqslant\! V_{CC}\leqslant\! 5.25V \end{array}$

PARAMETER		TEST CONDITIONS	S82S130/131			N82S130/131			
		TEST CONDITIONS ¹	MIN	TYP ²	MAX	MIN	TYP ²	MAX	UNIT
VoL	"0" Output Voltage	I _{OUT} = 16mA			0.5			0.45	V
lock	Output Leakage Current (82S130)	CE = "1", V _{OUT} = 5.5V			60			40	μΑ
I _{O(OFF)}	Hi-Z State Output Current (82S131)	<u>CE</u> = "1", V _{OUT} = 0.5V <u>CE</u> = "1", V _{OUT} = 5.5V			-60 60			-40 40	μΑ μΑ
V _{OH}	High Level Output Voltage (82S131)	<u>CE</u> = "0", I _{OUT} = -2.4mA, "1" STORED	2.4			2.4			V
C _{IN}	Input Capacitance	$V_{IN} = 2.0V, V_{CC} = 5.0V$		5			5		pF
C _{OUT}	Output Capacitance	$V_{OUT} = 2.0V, V_{CC} = 5.0V$		8			8		pF
I _{IL}	"0" Input Current	$V_{IN} = 0.45V$			- 150			-100	μΑ
I _{IH}	"1" Input Current	$V_{IN} = 5.5V$			50		,	40	μΑ
VIL	"0" Level Input Voltage			'	.80			.85	V
V _{IH}	"1" Level Input Voltage		2.0			2.0			v
Icc	V _{CC} Supply Current			120	140		120	140	mA
V _{IC}	Input Clamp Voltage	$I_N = -18mA$		-0.8	-1.2		-0.8	-1.2	v
los	Output Short Circuit Current (82S131)	V _{OUT} = 0V	- 15		-85	-20		-70	mA

SWITCHING CHARACTERISTICS

S82S130/131 N82S130/131 -55°C \leq T_A \leq +125°C, 4.5 \leq V_{CC} \leq 5.5V 0°C \leq T_A \leq +75°C, 4.75 \leq V_{CC} \leq 5.25V

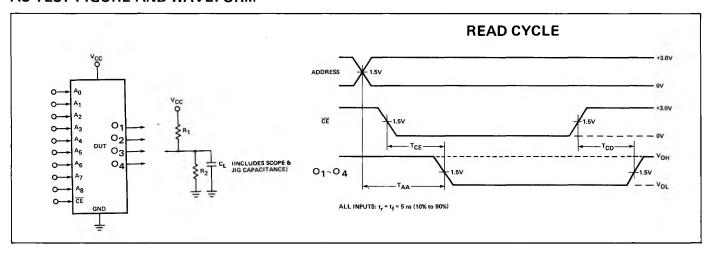
DADAMETED	TEST CONDITIONS ¹	S82S130/131 N82S130/131						
PARAMETER	1EST CONDITIONS	MIN	TYP ²	MAX	MIN	TYP ²	MAX	UNIT
Propagation Delay		•						
T _{AA} Address to Output	C _L = 30pF		40	70		40	50	ns
T _{CD} Chip Disable to Output	$C_L = 30pF$ $R_1 = 270\Omega$		20	30		20	30	ns
T _{CE} Chip Enable to Output	$R_2 = 600\Omega$		20	30		20	30	ns

NOTES:

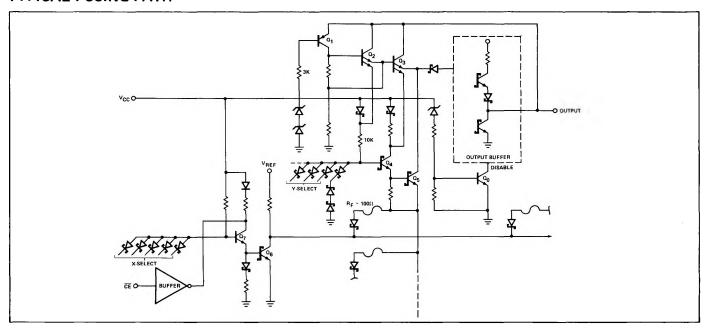
^{1.} Positive current is defined as into the terminal referenced.

^{2.} Typical values are at V_{CC} = 5.0V, T_A = +25°C.

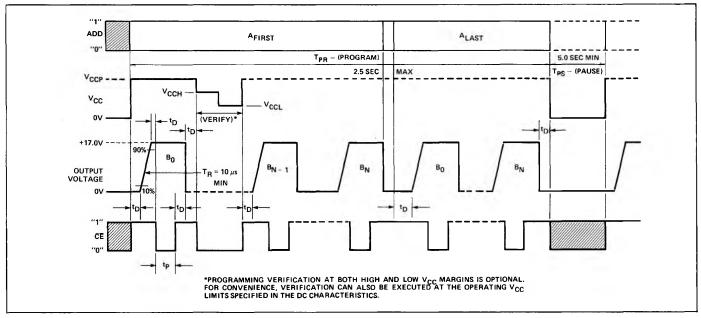
AC TEST FIGURE AND WAVEFORM



TYPICAL FUSING PATH



TYPICAL PROGRAMMING SEQUENCE



PROGRAMMING SPECIFICATIONS (Testing of these limits may cause programming of device.) T_A = +25°C

	242445752	TEST SOURITIONS					
	PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT	
Power Sup	oply Voltage						
V _{CCP} ¹	To Program	I _{CCP} = 350 ± 50mA (Transient or steady state)	8.5	8.75	9.0	٧	
V _{CCH}	Upper Verify Limit		5.3	5.5	5.7	V	
V_{CCL}	Lower Verify Limit		4.3	4.5	4.7	V	
V_S^3	Verify Threshold		0.9	1.0	1.1	V	
I _{CCP}	Programming Supply Current	$V_{CCP} = +8.75 \pm .25V$	300	350	400	mA	
Input Vol	tage					-	
V _{IH}	Logical "1"		2.4		5.5	V	
VIL	Logical "0"		0	0.4	0.8	V	
Input Cur	rent						
I _{IH}	Logical "1"	V _{IH} = +5.5V			50	μΑ	
I _{IL}	Logical "0"	V _{1L} = +0.4V			-500	μΑ	
V _{OUT} ²	Output Programming Voltage	I_{OUT} = 200 ± 20mA (Transient or steady state)	16.0	17.0	18.0	٧	
lout	Output Programming Current	V _{OUT} = +17 ± 1V	180	200	220	mA	
TR	Output Pulse Rise Time		10		50	μs	
tp	CE Programming Pulse Width		1		2	ms	
t _D	Pulse Sequence Delay		10			μs	
T _{PR} 5	Programming Time	V _{CC} = V _{CCP}			2.5	sec	
T _{PS}	Programming Pause	V _{CC} = 0V	5	i		sec	
$\frac{{T_{PR}^4}}{{T_{PR}} + {T_{PS}}}$	Programming Duty Cycle				33	%	

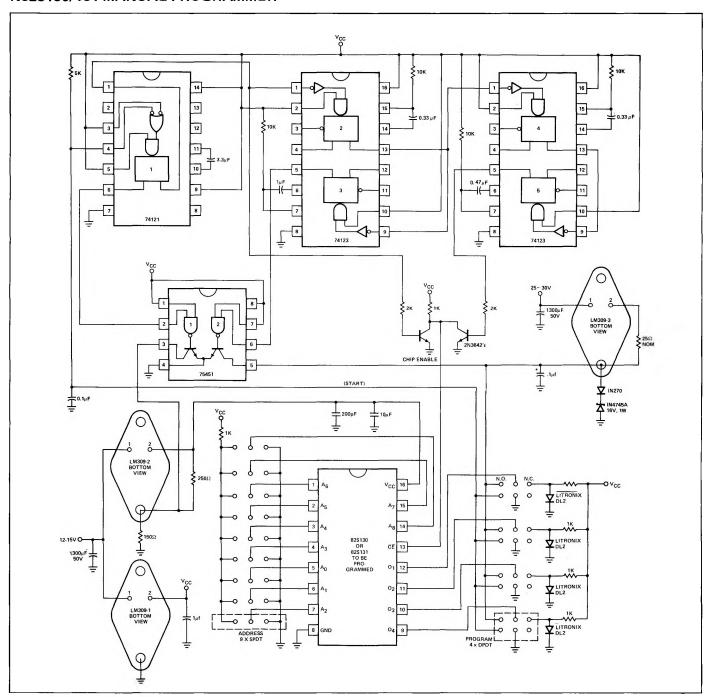
PROGRAMMING PROCEDURE

- 1. Terminate all device outputs with a 10K $\!\Omega$ resistor to VCC.
- 2. Select the Address to be programmed, and raise V_{CCP} to $V_{CCP} = 8.75 \pm .25V$.
- 3. After 10μ s delay, apply $V_{OUT} = +17 \pm 1V$ to the output to be programmed. Program one output at the time.
- 4. After 10μ s delay, pulse the \overline{CE} input to logic "0" for 1 to 2 ms.
- 5. After $10\mu s$ delay, remove +17V from the programmed output.
- 6. To verify programming, after 10 μ s delay, lower V_{CC} to V_{CCH} = +5.5 \pm .2V, and apply a logic "0" level to the $\overline{\text{CE}}$ input. The programmed output should remain in the "1" state. Again, lower V_{CC} to V_{CCL} = +4.5 \pm .2V, and verify that the programmed output remains in the "1" state.
- 7. Raise V_{CC} to $V_{CCP} = 8.75 \pm .25V$, and repeat steps 3 through 6 to program other bits at the same address.
- 8. After 10μ s delay, repeat steps 2 through 7 to program all other address locations.

NOTES:

- 1. Bypass V_{CC} to GND with a 0.01 μ F capacitor to reduce voltage spikes.
- 2. Care should be taken to insure the 17 ± 1V output voltage is maintained during the entire fusing cycle. The recommended supply is a constant current source clamped at the specified voltage limit.
- 3. V_S is the sensing threshold of the PROM output voltage for a programmed bit. It normally constitutes the reference voltage applied to a comparator circuit to verify a successful fusing attempt.
- Continuous fusing for an unlimited time is also allowed, provided that a 33% duty cycle is maintained. This may be accomplished by following each Program-Verify cycle with a Rest period (V_{CC} = 0V) of 4ms.
- 5. On the first programming attempt (from cold start) a maximum limit of 5 sec. is allowed. In most cases, depending on the truth table, this will decrease total programming time.

N82S130/131 MANUAL PROGRAMMER



TIMING SEQUENCE

